03/02/2015 503200947

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT3247564

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
KANGHO LEE	12/23/2014
CHANDO PARK	12/23/2014
JIMMY KAN	01/05/2015
MATTHIAS GEORG GOTTWALD	02/24/2015
XIAOCHUN ZHU	01/05/2015
SEUNG HYUK KANG	12/23/2014

RECEIVING PARTY DATA

Name:	QUALCOMM INCORPORATED
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121-1714

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	14558103	

CORRESPONDENCE DATA

Fax Number: (512)327-5575

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 512-327-5515

Email: dwade@tlgiplaw.com **TOLER LAW GROUP Correspondent Name:** 8500 BLUFFSTONE COVE Address Line 1:

Address Line 2: SUITE A201

Address Line 4: AUSTIN, TEXAS 78759

ATTORNEY DOCKET NUMBER:	141413
NAME OF SUBMITTER:	DAVID WADE
SIGNATURE:	/David Wade/
DATE SIGNED:	03/02/2015

Total Attachments: 6 source=141413_Assignment#page1.tif source=141413_Assignment#page2.tif source=141413_Assignment#page3.tif source=141413_Assignment#page4.tif source=141413_Assignment#page5.tif source=141413_Assignment#page6.tif

ASSIGNMENT

WHEREAS, WE,

- 1. Kangho LEE, a citizen of Korea, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714 and a resident of San Diego, CA,
- 2. Chando PARK, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714 and a resident of San Diego, CA,
- 3. Jimmy KAN, a citizen of Canada, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714 and a resident of San Diego, CA,
- 4. Matthias Georg Gottwald, a citizen of Germany, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714 and a resident of Leuven, Belgium,
- 5. Xiaochun ZHU, a citizen of the People's Republic of China, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714 and a resident of San Diego, CA.
- 6. Seung Hyuk KANG, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714 and a resident of San Diego, CA,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to MAGNETIC ETCH STOP LAYER FOR SPIN-TRANSFER TORQUE MAGNETORESISTIVE RANDOM ACCESS MEMORY MAGNETIC TUNNEL JUNCTION DEVICE (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged. WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States,

including but not limited to U.S. Application No(s). 14/558,103 filed December 2, 2014, Qualcomm Reference No. 141413, and all provisional applications relating thereto, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument:

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

whatsoever conflicting with these presents. Kangho LEE Done at Son Diego, on 12/23//4
LOCATION DATE Matthias Georg GOTTWALD Done at LOCATION On DATE Xiaochun ZHU Done at Sary Dream, on 12/22/2014 Seung Hyak KANG

AND WE HEREBY covenant that WE will not execute any writing or do any act

ASSIGNMENT

WHEREAS, WE.

- 1. Kangho LEE, a citizen of Korea, having a mailing address located at 5775 Morehouse Drive. San Diego, CA 92121-1714 and a resident of San Diego, CA,
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- Seung Hyuk KANG, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714 and a resident of San Diego, CA.

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to MAGNETIC ETCH STOP LAYER FOR SPIN-TRANSFER TORQUE MAGNETORESISTIVE RANDOM ACCESS MEMORY MAGNETIC TUNNEL JUNCTION DEVICE (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive. San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged. WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States.

including but not limited to U.S. Application No(s). 14/558,103 filed December 2, 2014, Qualcomm Reference No. 141413, and all provisional applications relating thereto, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument:

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNUE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance:

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEF, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

	_, on	
LOCATION	DATE	Kangho LEE
LOCATION	, on	
LOCATION	DAIL	Chando PARK
LOCATION	, on	Jimmy KAN
LEUVEV LOCATION	, on 2015/01/21	Matthias Georg GOTTWALD
LOCATION	, on	Xiaochua ZHU
LOCATION	, on	Count House PARC
	LOCATION LOCATION LOCATION	LOCATION DATE LOCATION DATE LOCATION DATE LOCATION DATE LOCATION DATE

PATENT REEL: 035118 FRAME: 0461

RECORDED: 03/02/2015